



## YES-CV200RFS Plasma Strip/Descum System

Powerful Cleaning Removes Photoresist, Polyimide and BCB;  
With Gentle Descum Function

### Specifications

<b>Hardware</b>	
Clean Room Compatibility	Class 10
Wafer Temperature Range	Ambient to 250 °C; 4 min. maximum ramp time
Capacity	Single wafer/pieces for 50mm - 200mm; Dual wafer/pieces for two 100mm
N <sub>2</sub> Flow Rate	1.7 SCFM
Process Gas Flow Rate	20-50 SCCM average
Process Gas Inputs	4 standard
Mass Flow Controllers	Optional, up to 4 for gas mixing
Interior Chamber Dimensions	25.4 cm (W) x 28.575 cm (D) x 4.978 cm (H) (10" x 11.25" x 1.96")
Hot Plate Process Area	49 in <sup>2</sup> maximum (200mm wafer)
Overall System Dimensions	59.7 cm (W) x 109.3 cm, door open (D) x 113.4 cm (H) (23.5" x 43" x 44.6")
Chamber Material	6061-T6 aluminum
Compliance	SEMI S2, CE, S8
<b>Software</b>	
Tool Control	PLC control of valves, temperature set points, plasma generation power, auto operation, touch screen interface
Number of Recipes	12 with load/save/loop/link capability
Range of Exposure Time	0-1200 seconds (20 minutes)
Resolution of Timer Setting	1 second
<b>Performance</b>	
RF Plasma Power	40 kHz, 100 – 1000 W capacitive, downstream
Process Pressure Measurement	Convection type pressure sensor, 0.1 mTorr to 1000 Torr (pressure measurement sensitive to process gas composition)
Vent Gas Consumption	0 SCF idle, 1.0 SCF peak, .44 SCF average
Reactant Gas Consumption	0 SCF idle, 4.2 x 10 <sup>-3</sup> peak and average
Heat Emission	920 watts average
Power Consumption with Pump	420W idle, 2100W peak, 1210W average
Throughput	1 wafer per minute (up to 200mm diameter), typically 90 seconds per wafer
Strip Rate	Up to 7,000 Angstroms per minute
Electron Shift	< 10mV electron shift in a 200A gate oxide variable plasma intensity
Uniformity (in wafer)	<10%
Cooling	Process chamber cooled by forced air convection
<b>Additional</b>	
Power Requirements	200-250V, 20 amps, 50/60 Hz, 1 phase
Power Supply	Automatic frequency tuning
System Weight	147.42 kg (325 lbs)
Shipping Weight, Crated (approx.)	295 kg (650 lbs.)
Crate Dimensions	139.7 cm (W) x 88.9 cm (D) x 144.78 cm (H) (55" x 35" x 57")



### Contact Us

When you're ready to run process tests, a demonstration can be arranged using your chemicals and samples. Call +352 450010 or visit us at [www.bitalu.lu](http://www.bitalu.lu)

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